SPEC. NO.: PS-5174	3-XXXXX-XXX	REVISION: C	
PRODUCT NAME:	PCI Express M.2 CONNE	CTOR	
PRODUCT NO:	51743 , 51749 , 51750,517	757,51763 SERIES	
PREPARED:	CHECKED:	APPROVED:	
PREPARED: Liu, Hua	CHECKED: Brave	APPROVED: Brave	

Aces P/N: 51743 , 51749 , 51750,51757,51763 series TITLE: PCI EXPRESS M.2 CONNECTOR RELEASE DATE: 2021/05/27. REVISION: C ECN No: ECN-003633 PAGE: 2 OF 12 1 2 3 4 5 6 7 8 MODULE CARD OPERATION......10 9

	Aces P/N: 51743 , 51749 , 51750,51757,51763 series
TITLE: PCI EXPRESS M.2 CONNEC	TOR

RELEASE DATE: 2021/05/27.	REVISION: C	ECN No: ECN-003633	PAGE: 3 OF 12

Revision History 1

Rev.	ECN #	Revision Description	Prepared	Date
0	ECN-1411348	NEW PRODUCT RELEASE	IH. LEE	2014/11/20
Α	ECN-1609162	ADD 51757 SERIES	LIUHUA	2016/09/09
В	ECN-1802062	ADD 51763 SERIES	CHENYA	2017/07/14
С	ECN-003633	Modify operating temperature	LIUHUA	2021/05/27

Aces P/N: **51743**, **51749**, **51750**, **51757**, **51763 series** TITLE: PCI EXPRESS M.2 CONNECTOR

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2 SCOPE

This specification covers performance, tests and quality requirements for PCI Express M.2 Connector

3 APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

- 4.1 Design and Construction
 - 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
 - 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.

4.2 Materials and Finish

Finish:

- 4.2.1 Contact: High performance copper alloy (Phosphor Bronze)
 - Finish: (a) Contact Area: Refer to the drawing.
 - (b) Under plate: Refer to the drawing.
 - (c) Solder area: Refer to the drawing.
 - 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
 - 4.2.3 Hold Down: High performance copper alloy(Phosphor Bronze)
 - (a) Under plate: Refer to the drawing.
 - (b) Solder area: Refer to the drawing.

4.3 Ratings

- 4.3.1 Working Voltage Less than 36 Volts AC (per pin)
- 4.3.2 Voltage: 50 Volts AC (per pin)
- 4.3.3 Current: 0.5 Amperes (per pin)
- 4.3.4 Operating Temperature : -40°C to +85°C

Aces P/N: 51743 , 51749 , 51750,51757,51763 series TITLE: PCI EXPRESS M.2 CONNECTOR

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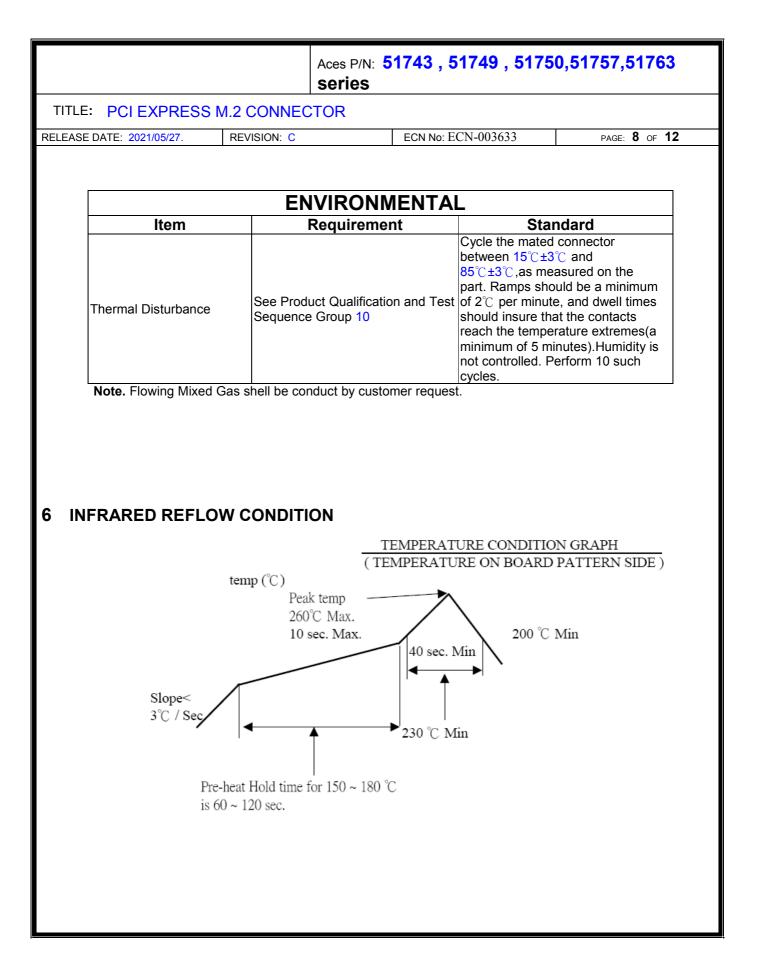
5 Performance

5.1. Test Requirements and Procedures Summary

ltem	Requirement	Standard						
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	f Visual, dimensional and functiona per applicable quality inspection plan.						
ELECTRICAL								
Item	Requirement	Standard						
Low Level Contact Resistance	Initial:55 mΩ Max. per contact After test:20 mΩ Max. change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)						
Insulation Resistance	500 MΩ Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)						
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 V AC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)						
Temperature Rise	30℃ Max. Change allowed	Mate connectors: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°((EIA-364-70,Method2)						

Aces P/N: 51743, 51749, 51750, 51757, 51763 series TITLE: PCI EXPRESS M.2 CONNECTOR RELEASE DATE: 2021/05/27. REVISION: C ECN No: ECN-003633 PAGE: 6 OF 12 MECHANICAL Requirement Standard Item The sample should be mounted in the tester and fully mated and Durability 60 Cycles unmated the number of cycles. (EIA-364-09) Perform 5 mate/unmate cycles if No evidence of physical damage the application requires up to 25 (EIA-364-09) over the life of the connector.20 Durability(precondition) cycles if the application requires 26~200;or,50 cycles if the application requires 201 or greater. Measure the force required to mate/unmate connector. Mating Forces Mating Force: 2.55 Kgf Max. (EIA-364-13 Method A) 15 minutes in each of 3mutually perpendicular directions. Both mating halves should be rigidly fixed so as not to contribute to the relative motion of one contact Vibration 1 microsecond Max. against another. The method of fixturing should be detailed in the test report. (EIA-364-28 Condition VII Condition letter D) Mate connectors to 250G(Ultrabook) and 285 G(Tablet) at 2 Shock (Mechanical) 1 microsecond Max. milliseconds half sine on all six axis. Manually mated/unmated the Reseating Appearance: No damage connector or socket perform 3 cycles.

Aces P/N: 51743, 51749, 51750, 51757, 51763 series TITLE: PCI EXPRESS M.2 CONNECTOR RELEASE DATE: 2021/05/27. REVISION: C ECN No: ECN-003633 PAGE: 7 OF 12 ENVIRONMENTAL Standard Item Requirement Pre Heat : 150°C ~ 180°C, 60~120sec. Resistance to Reflow See Product Qualification and Test Heat: 230°C Min., 40sec Min. Sequence Group 11 (Lead Free) Soldering Heat Peak Temp. : 260°C Max, 10sec Max. Mate module and subject to follow condition for 10 cycles. 1 cycles: See Product Qualification and Test -55 +0/-3 °C, 30 minutes. Thermal Shock Sequence Group 2 +85 +3/-0 °C, 30 minutes. (EIA-364-32, method A test condition I) Cycle the connector or socket between 25°C ±3°C at 80±3% RH and 65°C ±3°C at 50%±3% RH. Ramp times should be 0.5hrs. and Cyclic Temperature & See Product Qualification and Test dwell times should be 1.0 hrs. Humidity Sequence Group 2 Dwell times start when the temperature and humidity have stabilized within the specified levels. Perform 24 such cycles. (EIA-364-31, Method III) Subject mated connectors to See Product Qualification and Test temperature life at 105°C for 120 Temperature Life Sequence Group 1 hours. (EIA-364-17, method A) Subject mated connectors to Temperature Life temperature life at 105℃ for 72 No physical damage (precondition) hours. (EIA-364-17, method A) Subject mated connectors to 5% salt-solution concentration, 35°C See Product Qualification and Test Salt Spray (I) Gold flash for 8 hours (Only For Gold Plating) Sequence Group 8 (II) Gold plating 5 u" for 96 hours. (EIA-364-26) Tin plating: Solder able area shall have Add then into solder bath, minimum of 95% solder coverage. Temperature at 245 ±5℃, for 4-5 Solder Ability Gold plating: sec. Solder able area shall have (EIA-364-52) minimum of 75% solder coverage Hand Soldering Appearance: No damage $T \ge 350^{\circ}$ C, 3sec at least. **Temperature Resistance**



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TLE: PCI EXPRESS M	.2 CO	NEC	TOR									
EASE DATE: 2021/05/27.	REVISIO	N: C	ECN No: ECN-003633			PAGE: 9 OF 12						
PRODUCT QUALIFI	CATIC	N AN	ND TE	ST S	EQU	ENCE	Ξ					
						Те	st Gro	up				
Test or Examination		1	2	3	4	5	6	7	8	9	10	11
			Test Sequence									
Examination of Product		1、6 9	1 \ 6 9 \ 12	1、6 9	1、7	1、4	1、3	1、7	1、5	1、3	1、5	1、3
Low Level Contact Resist	ance	2 \ 5 8	2 \ 5 8 \ 11	2、5 8	2、6			2 \ 4 6	2、4		2、4	
Insulation Resistance						2						
Dielectric Withstanding Vo	oltage					3						
Mating / Unmating Forces					3、5							
Durability					4							
Durability(precondition)		3	3	3				3				
Temperature Rise							2					
Vibration				7								
Shock (Mechanical)								5				
Reseating		7	10									
Thermal Shock			4									
Cyclic Temperature & Hur	nidity		7									
Temperature Life		4										
Temperature Life(precond	ition)			4								
Salt Spray									3			
Solder Ability										2		
Thermal Disturbance											3	
Resistance to Soldering H	eat											2
Sample Size		4	4	4	4	4	4	4	4	4	4	4

